



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q62153

Takuo FUNAYA, et al.

Appln. No.: 09/730,849

Group Art Unit: 2818

Confirmation No.: 9306

Examiner: D. NHU

Filed: December 7, 2000

For: ELECTRONIC DEVICE ASSEMBLY AND A METHOD OF CONNECTING
ELECTRONIC DEVICES CONSTITUTING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated April 15, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please enter the following amended claims:

3. (ONCE AMENDED) An assembly as claimed in claim 2, wherein sold resin layer is so patterned as to be absent around wiring portions protruding from said electronic devices, around passive devices mounted between said electronic devices, around portions of circuit surfaces of said electronic devices where resin forming said resin layer effects a device characteristic, around electrode pads, and around bumps formed on said electrode pads.

#11/a
mushka
6/19/03

RECEIVED
JUN 17 2003
10 2500 MAIL ROOM

Ad
B18
a